

MOSFET Bare Die on KGD UV Tape Array

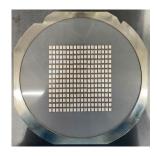
General Storage Requirements

Products are stored on wafer frame and tape, in a nitrogen purged cabinet away from direct sunlight. If cabinet not available, then vacuum sealed in MBB.

ESD mitigation protocols must be followed at all times when handling.

Applies to the following products

	Part #	Die Size
\rightarrow	XXXXX - KUV	Any





Device	Array Size	Quantity per Array	X & Y Die-to-Die Spacing (um)
GP2T020A120X-KUV	18 x 14	252	1100
GP2T040A120X-KUV	26 x 16	416	1100
GP2T080A120X-KUV	26 x 26	676	1100

Environmental Storage Recommendation:

Environmental Factor	Values	Unit
Storage Temperature (Ts)	15 < T _S < 25	°C
Maximum Humidity	<30	%RH
Maximum Shelf Life	6	Months
N2 cabinet particle count	Class 6 per ISO 14644	Class

Additional UV Exposure:

Prior to shipment, the tape has been exposed to UV light to lower the adhesion strength, but further reduction in adhesion can be done by additional exposure of 450mJ/cm2 dose @ 365nm. However, care must be taken to minimize heating of the tape.

Notes

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Rev.	Release Date	Description of Change
1	4/22/2024	Initial release